

### DZ2705600L Silicon epitaxial planar type

# For constant voltage / For surge absorption circuit DZ2S056 in SSSMini2 type package

#### Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: DJ

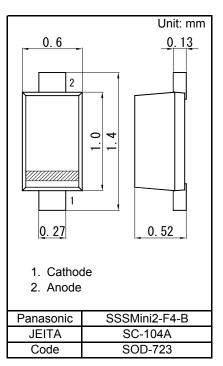
#### Packaging

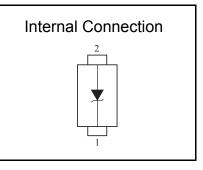
Embossed type (Thermo-compression sealing) : 10 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C							
Parameter	Symbol	Rating	Unit				
Repetitive peak forward current	IFRM	200	mA				
Total power dissipation *1	PT	120	mW				
Electrostatic discharge <sup>*2</sup>	ESD	±15	kV				
Junction temperature	Tj	150	°C				
Operating ambient temperature	Topr	-40 to +85	°C				
Storage temperature	Tstg	-55 to +150	°C				

Storage temperatureTstg-55 to +150Note)\*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)Solder in ( 0.4 mm x 0.3 mm)

\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





#### Electrical Characteristics Ta = $25 \circ C \pm 3 \circ C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage *1, *2	VZ	IZ = 5 mA	5.32		5.88	V	
Zener operating resistance	RZ	IZ = 5 mA			40	Ω	
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω	
Reverse current	IR	VR = 2.5 V			0.5	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		1.6		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

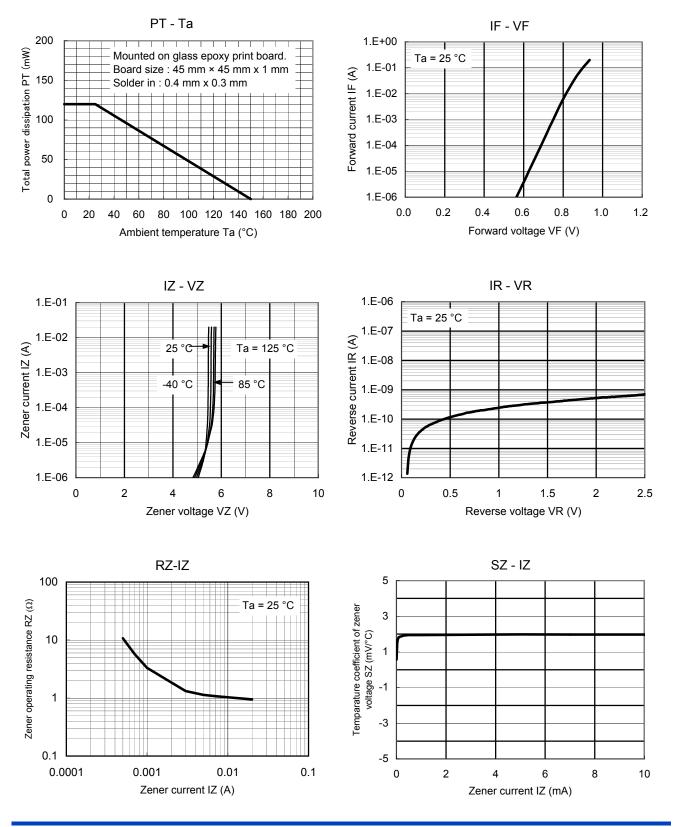
\*2 VZ guaranted 20 ms after current flow.

\*3 Tj = 25°C to 150°C

#### Established : 2009-10-30 Revised : 2013-08-28



### Technical Data (reference)

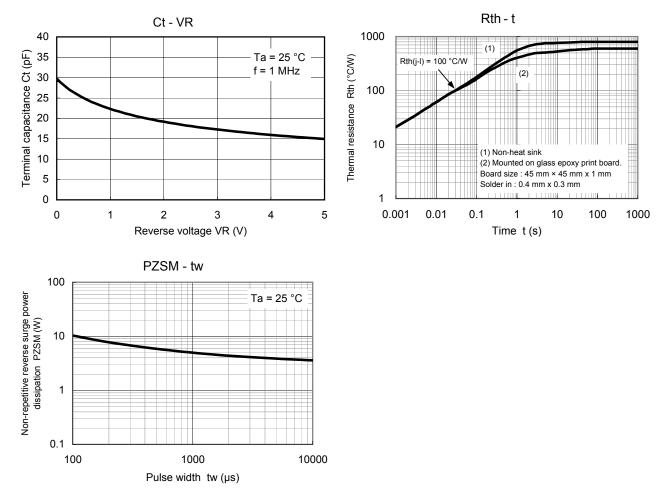


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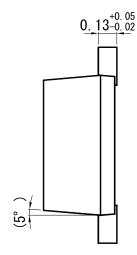
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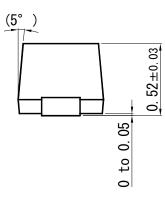


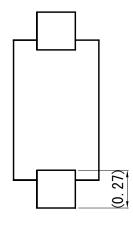


## SSSMini2-F4-B

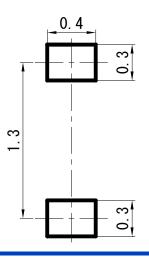
0.60±0.05 2 2 50 0.07-0.03 0.27-0.03 0.27-0.03 0.05 







Land Pattern (Reference) (Unit: mm)



Established : 2009-10-30 Revised : 2013-08-28 Unit: mm

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